

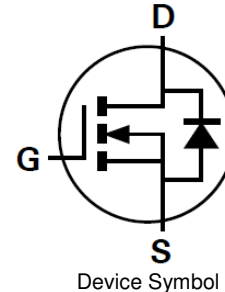
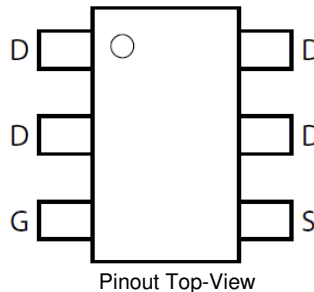
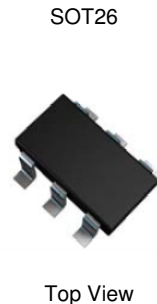
100V N-CHANNEL ENHANCEMENT MODE MOSFET
Product Summary

$V_{(BR)DSS}$	Max $R_{DS(on)}$	Max I_D $T_A = +25^\circ\text{C}$ (Note 7)
100V	230m Ω @ $V_{GS} = 10\text{V}$	1.9A
	300m Ω @ $V_{GS} = 4.5\text{V}$	1.68A

Description and Applications

This MOSFET utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. It is ideal for high-efficiency, low voltage, power management applications.

- DC - DC Converters
- Power Management Functions
- Disconnect Switches
- Motor Control


Features and Benefits

- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- SOT26 Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 standards for High Reliability**
- **PPAP Available (Note 4)**

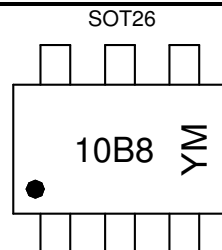
Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe.
Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.015 grams (Approximate)

Ordering Information (Note 5)

Part Number	Compliance	Case	Packing
ZXMN10B08E6QTA	Automotive	SOT26	3,000
ZXMN10B08E6QTC	Automotive	SOT26	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


10B8 = Product Type Marking Code
 YM = Date Code Marking
 Y or $\bar{Y}$ = Year (ex: C = 2015)
 M or $\bar{M}$ = Month (ex: 9 = September)

Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025
Code	C	D	E	F	G	H	I	J	K	L	M

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

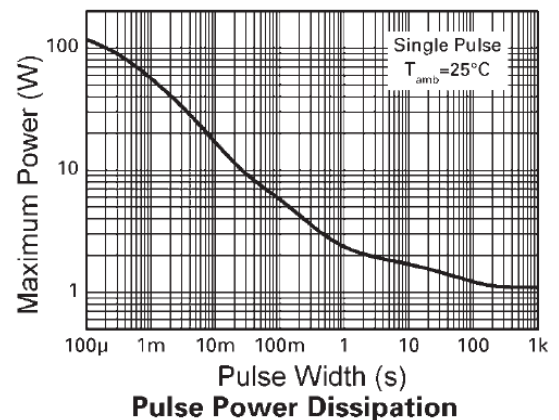
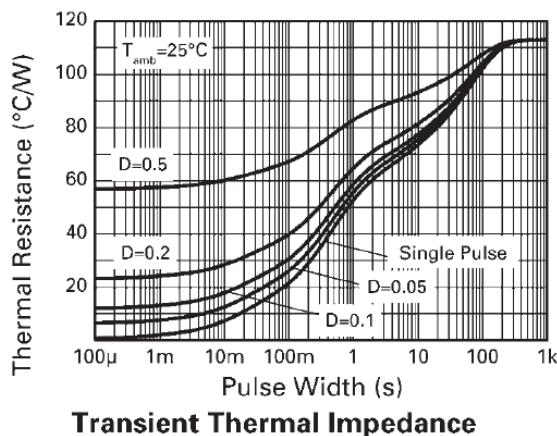
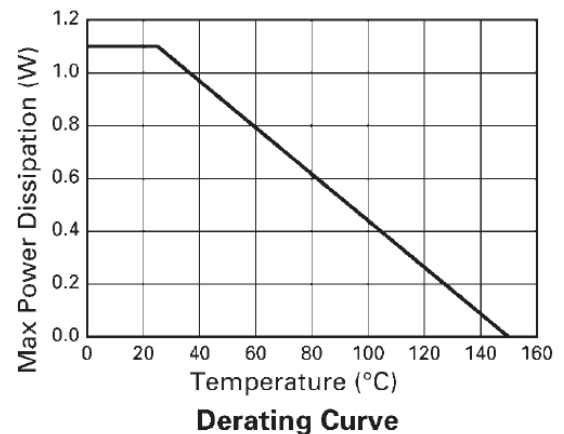
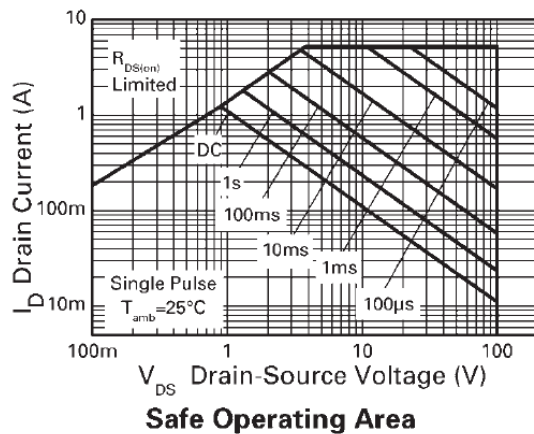
Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	100	V
Gate-Source Voltage			V _{GS}	±20	V
Continuous Drain Current	V _{GS} = 10V	(Note 7)	I _D	1.9	A
		T _A = +70 °C (Note 7)		1.5	
		(Note 6)		1.6	
Pulsed Drain Current		(Note 8)	I _{DM}	9	A
Continuous Source Current (Body Diode)		(Note 7)	I _S	2.5	A
Pulsed Source Current (Body Diode)		(Note 8)	I _{SM}	9	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation (Note 6)		P _D	1.1	W
Linear Derating Factor			8.8	mW/°C
Power Dissipation (Note 7)		P _D	1.7	W
Linear Derating Factor			13.6	mW/°C
Thermal Resistance, Junction to Ambient	(Note 6)	R _{θJA}	113	°C/W
	(Note 7)		73	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

- Notes:
6. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
 7. For a device surface mounted on FR4 PCB measured at t ≤ 5 secs.
 8. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.02, pulse width 300μs - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

Thermal Characteristics

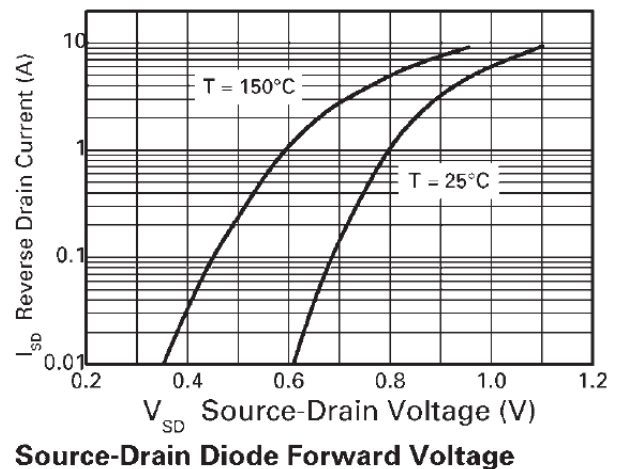
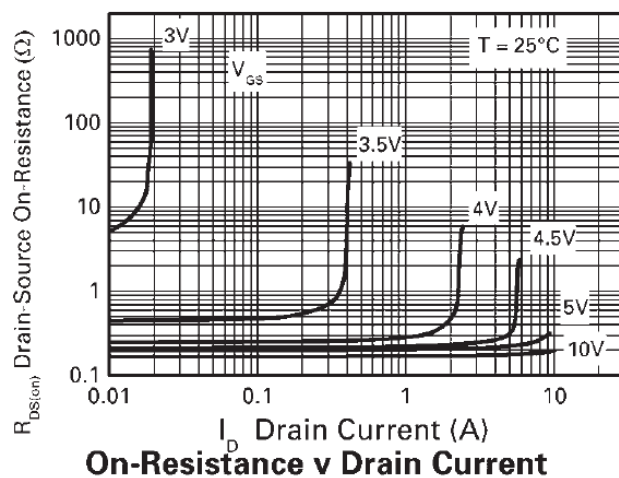
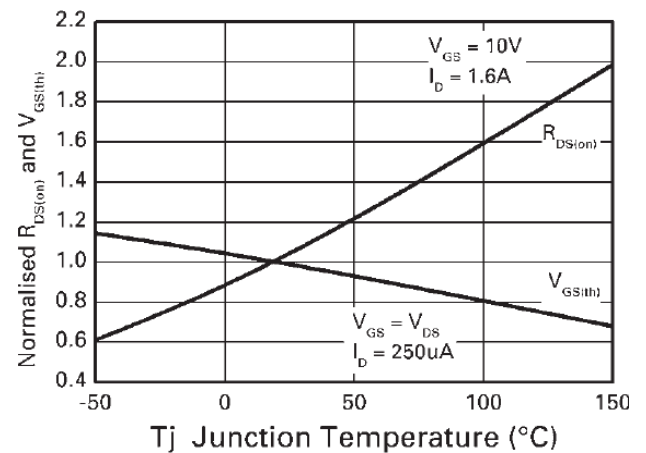
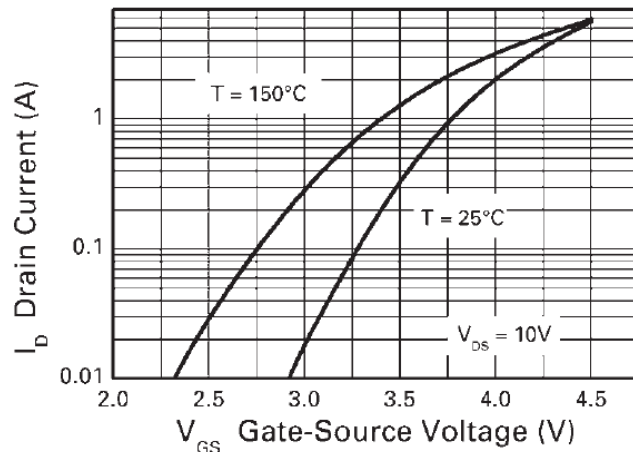
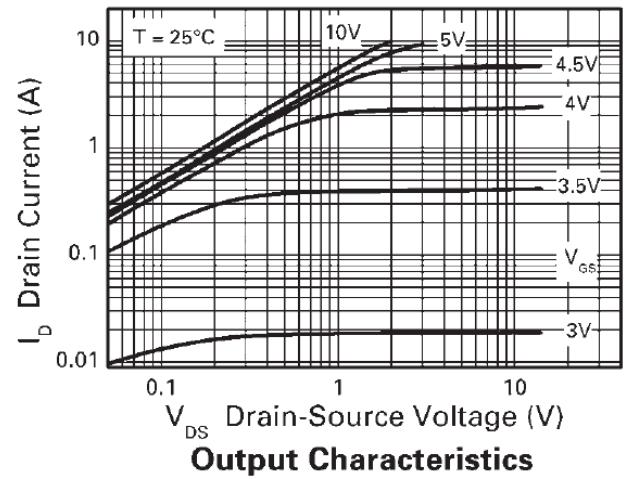
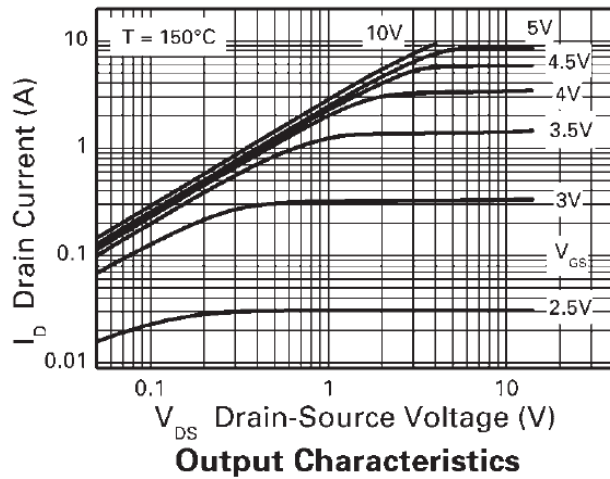


Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

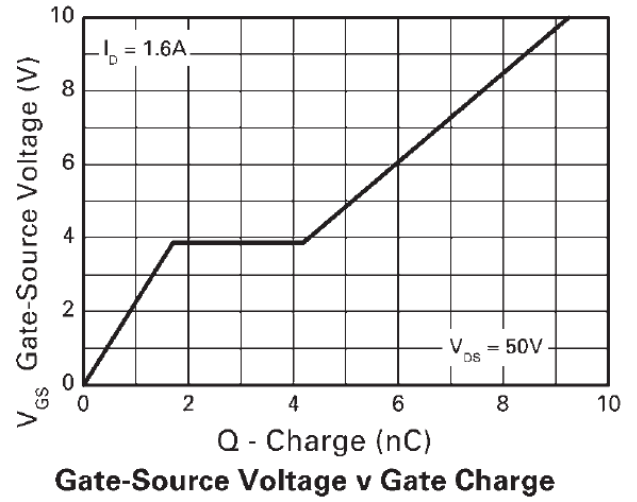
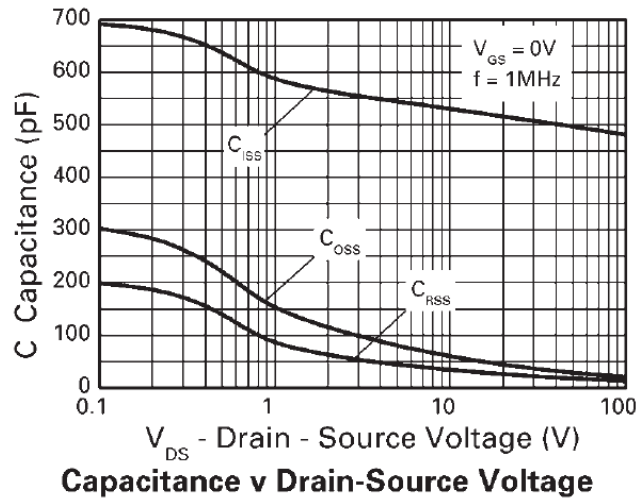
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	100	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	0.5	μA	V _{DS} = 100V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	1.0	—	3.0	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 9)	R _{DS(ON)}	—	—	0.23	Ω	V _{GS} = 10V, I _D = 1.6A
				0.30		V _{GS} = 4.5V, I _D = 1.4A
				0.50		V _{GS} = 4.3V, I _D = 1.1A
Forward Transconductance (Notes 9 & 11)	g _{fs}	—	4.8	—	S	V _{DS} = 15V, I _D = 1.6A
Diode Forward Voltage (Note 9)	V _{SD}	—	0.85	0.95	V	T _J = +25 °C, I _S = 2.0A, V _{GS} = 0V
DYNAMIC CHARACTERISTICS (Note 11)						
Input Capacitance	C _{iss}	—	497	—	pF	V _{DS} = 50V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	29	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	18	—	pF	
Gate Charge (Note 10)	Q _g	—	5.0	—	nC	V _{DS} = 50V, V _{GS} = 5V, I _D = 1.6A
Total Gate Charge (Note 10)	Q _g	—	9.2	—	nC	V _{DS} = 50V, V _{GS} = 10V, I _D = 1.6A
Gate-Source Charge (Note 10)	Q _{gs}	—	1.7	—	nC	
Gate-Drain Charge (Note 10)	Q _{gd}	—	2.5	—	nC	
Turn-On Delay Time (Note 10)	t _{d(on)}	—	2.9	—	ns	V _{DD} = 50V, I _D = 1.0A, R _G ≅ 6.0Ω, V _{GS} = 10V
Turn-On Rise Time (Note 10)	t _r	—	2.1	—	ns	
Turn-Off Delay Time (Note 10)	t _{d(off)}	—	12.1	—	ns	
Turn-Off Fall Time (Note 10)	t _f	—	5.0	—	ns	
Reverse Recovery Time	t _{rr}	—	32	—	ns	T _J = +25 °C, I _F = 1.7A, di/dt = 100A/μs
Reverse Recovery Charge	Q _{rr}	—	40	—	nC	

Notes: 9. Measured under pulsed conditions. Width ≤ 300μs. Duty cycle ≤ 2%.
10. Switching characteristics are independent of operating junction temperature.
11. For design aid only, not subject to production testing.

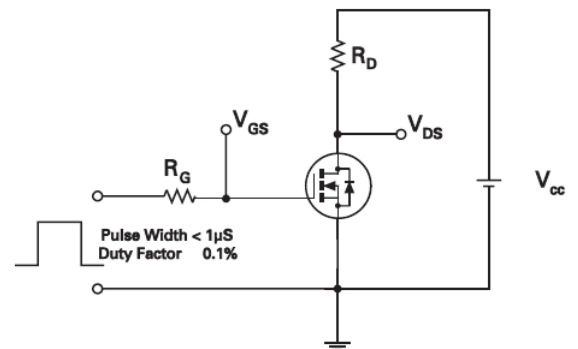
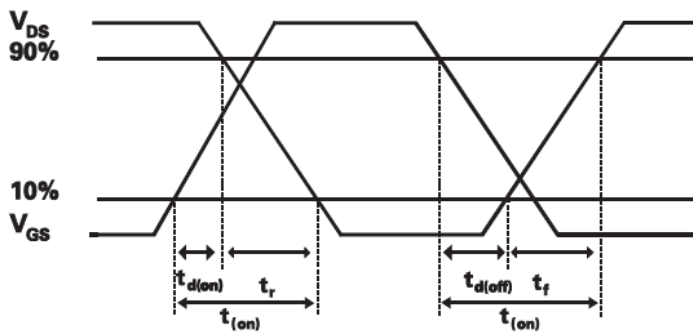
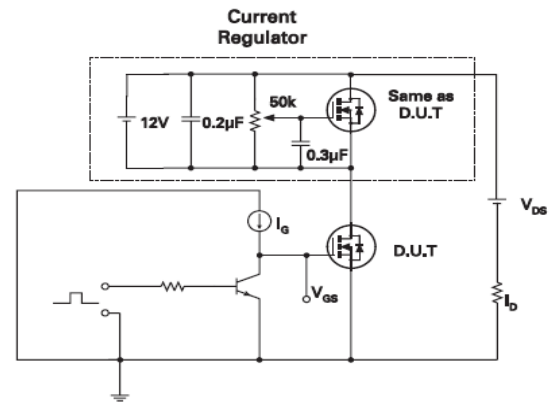
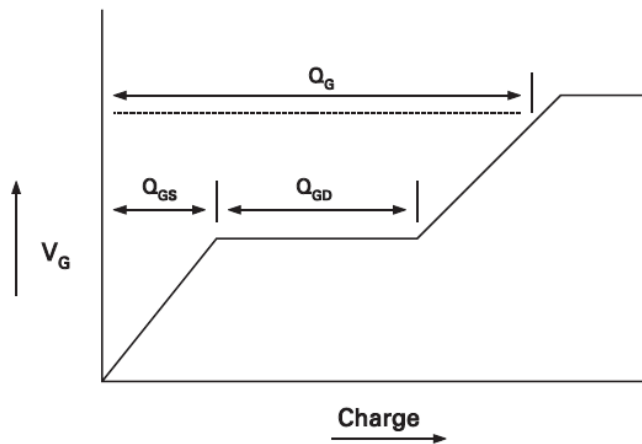
Typical Characteristics



Typical Characteristics (continued)

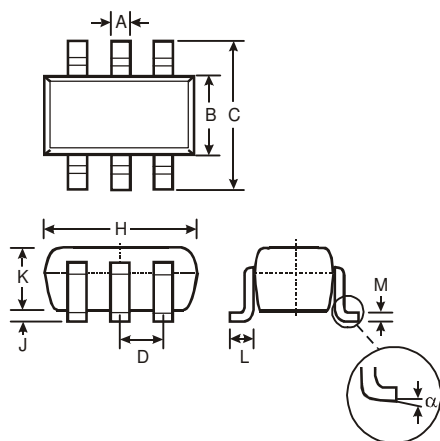


Test Circuits



Package Outline Dimensions

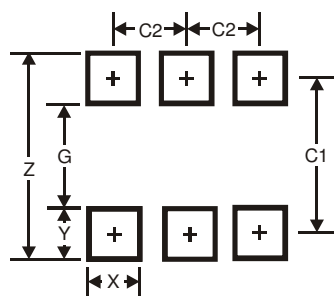
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

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